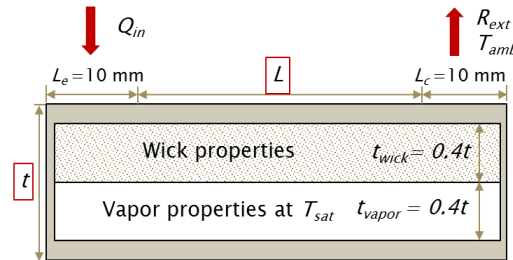


## Objectives

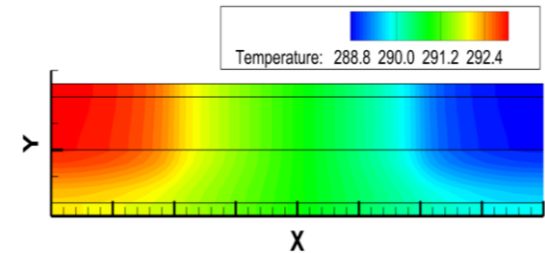
- Evaluation and model-based design of ultra-thin heat pipes for low power applications
- Validate and improve heat pipe models to capture important governing mechanisms
- Generate comprehensive design guidelines

## Approach

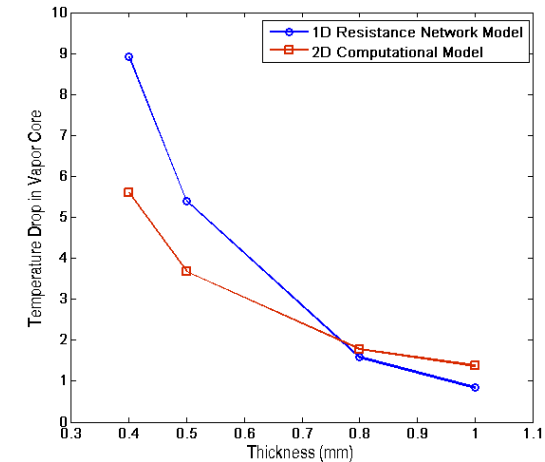
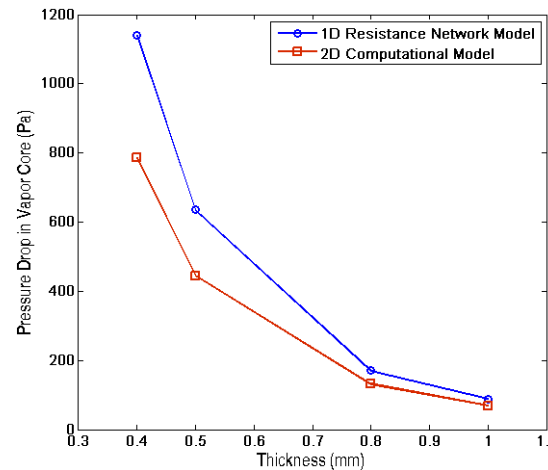
- Numerical modeling using 1D resistance network model and 2D computational model
- Compare performance with heat spreader
- Identify important transport mechanisms



Numerical Case and Geometry



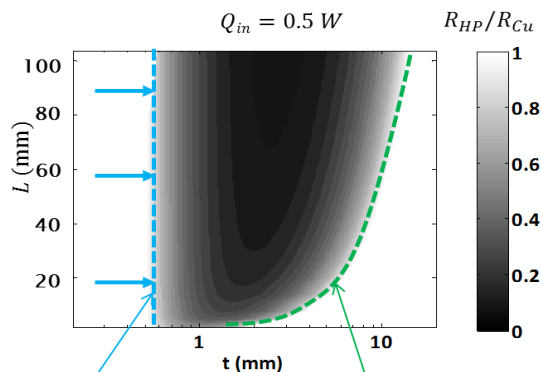
Temperature Contours



Comparison Between 1D and 2D Models

## Selected Publications

- Vadakkan, U., Murthy, J. Y., and Garimella, S. V., 2003, "Transient Analysis of Flat Heat Pipes," *Procs. ASME SHTC*, HT2003-47349.
- Prasher, R., 2003, "A Simplified Conduction Based Modeling Scheme for Design Sensitivity Study of Thermal Solution Utilizing Heat Pipe and Vapor Chamber Technology," *ASME JEP*, pp. 378-385



### Vapor Density Crossover:

Vapor pressure drop does not cause capillary limit, but has increasing effective  $\Delta T$

### Length-to-Thickness Ratio Crossover:

Relatively thick and short heat pipes cannot compete against  $L/kA$  conduction resistance [4]